

## GLASS PASSIVATED SURFACE MOUNT BRIDGE RECTIFIERS

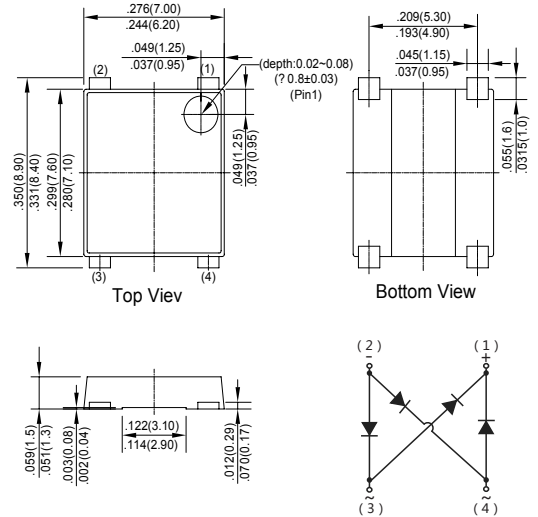
### Features

- ◆ Glass Passivated Chip Junction
- ◆ Reverse Voltage - 60 V
- ◆ Forward Current - 5.0 A
- ◆ High Surge Current Capability
- ◆ Designed for Surface Mount Application

**UMSB**
**ROHS  
COMPLIANT**

### Mechanical Data

Case: JEDEC UMSB molded plastic body  
 Terminals: Solderable per MIL-STD-750, Method 2026A  
 Polarity: Polarity symbol marking on body  
 Mounting Position: Any  
 Weight : 0.00824 ounce, 0.2337 grams



Dimensions in inches and (millimeters)

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbols	MDD MSB56	Units
Marking Code			
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	60	V
Maximum RMS voltage	$V_{RMS}$	42	V
Maximum DC Blocking Voltage	$V_{DC}$	60	V
Maximum Average Forward Rectified Current	$I_O$	5	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$	80	A
Maximum Forward Voltage @ $I_F = 3A$ @ $I_F = 5A$	$V_F$	0.45(TYP) 0.59	V
Maximum DC Reverse Current at Rated DC Blocking Voltage @ $T_a = 25^\circ C$	$I_R$	0.3	mA
Typical Junction Capacitance (Note 1)	$C_j$	300	pF
Operating Temperature Range	$T_j$	-55 ~ +150	°C
Storage Temperature Range	$T_{stg}$	-55 ~ +150	°C

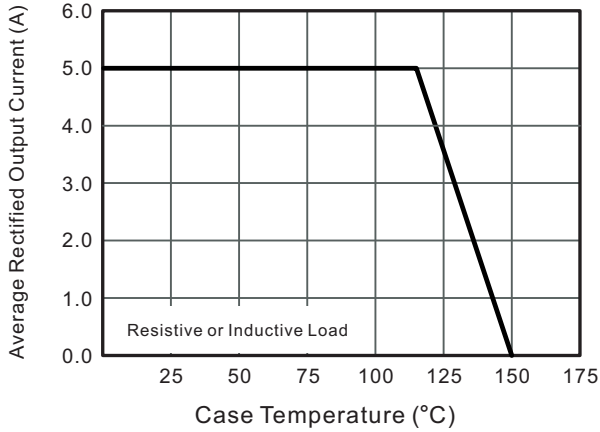
Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" ( 3.81×3.81 cm ) copper pad.

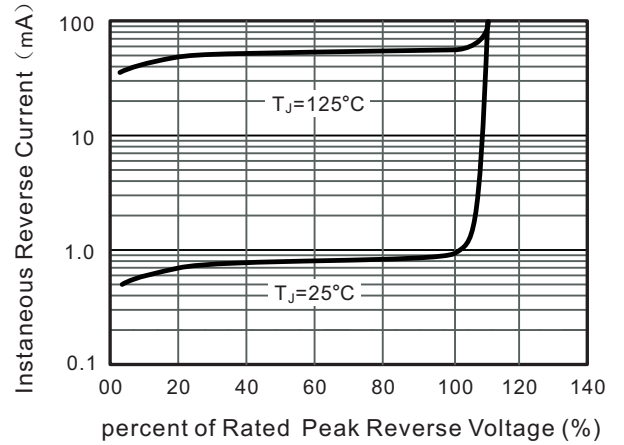


**Typical Characteristics**

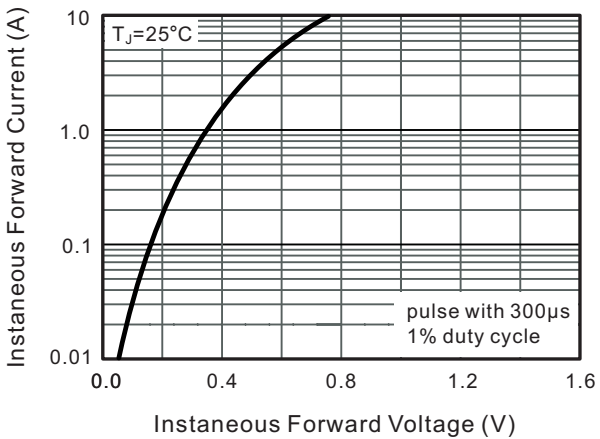
**Fig.1 Average Rectified Output Current Derating Curve**



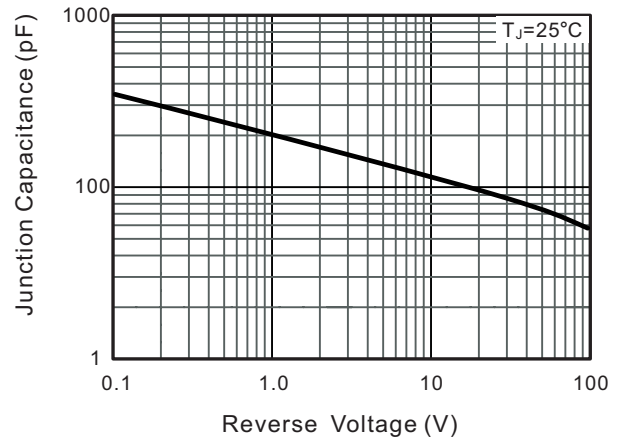
**Fig.2 Typical Reverse Characteristics**



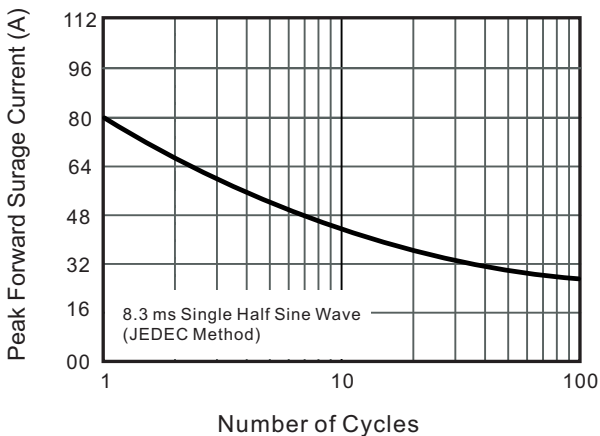
**Fig.3 Typical Instantaneous Forward Characteristics**



**Fig.4 Typical Junction Capacitance**

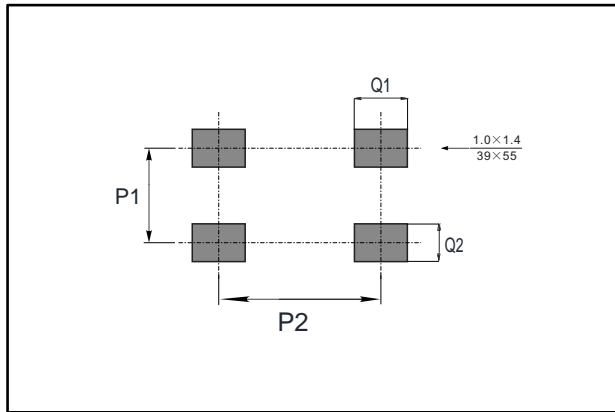


**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**



The curve above is for reference only.

## Suggested Pad Layout



Dim	Min
P1	5.1
P2	7.1
Q1	1.8
Q2	1.3

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